Claims

1. An electronic device comprising:

a housing comprising a coupling region; and

a printed circuit board (PCB) comprising an overlap region that overlaps the coupling region and a non-overlap region that does not overlap the coupling region;

wherein the PCB comprises a plurality of metal layers and a plurality of lines,

wherein the PCB comprises a void portion in which a portion of at least one metal layer close to the coupling region among the plurality of metal layers is not formed, wherein the void portion is not disposed in a metal layer that is farthest from the coupling region among the plurality of metal layers.

2. The electronic device of claim 1, wherein the void portion is disposed only in a metal layer that is closest to the coupling region among the plurality of metal layers, in the non-overlap region.

3. The electronic device of claim 1, wherein the plurality of lines is provided in both the overlap region and the non-overlap region.

4. The electronic device of claim 1, further comprising:

an antenna comprising a ground portion,

wherein the ground portion is electrically connected to a metal layer that is closest to the coupling region among the plurality of metal layers.

5. The electronic device of claim 1, further comprising:

an antenna,

wherein the housing comprises an accommodating portion configured to accommodate the antenna,

wherein the coupling region is at a boundary of the accommodating portion.

6. The electronic device of claim 1, wherein the plurality of lines are lines through which signals pass.

7. The electronic device of claim 1, further comprising:

an antenna comprising a ground portion that is connected to the plurality of lines or forms at least a portion of the plurality of lines.

8. The electronic device of claim 1, wherein the housing has a bottom surface comprising the coupling region and a non-coupling region that is different from the coupling region, and

wherein the housing further comprises a protruding rib that protrudes from the coupling region of the bottom surface and contacts a metal layer closest to the coupling region among the plurality of metal layers.

9. The electronic device of claim 8, wherein the housing further comprises:

a hole formed on the protruding rib; and

a fixing member coupled to the hole and configured to fix the PCB to the protruding rib.

10. The electronic device of claim 8, wherein the housing comprises a burr formed in the protruding rib and meeting a metal layer closest to the coupling region among the plurality of metal layers.

11. The electronic device of claim 1, wherein the PCB further comprises at least one dielectric layer on or under at least one metal layer among the plurality of metal layers.

12. The electronic device of claim 1, wherein the void portion is in the non-overlap region.

13. The electronic device of claim 1, wherein the void portion is in at least a portion of the overlap region and at least a portion of the non-overlap region.

14. The electronic device of claim 1, wherein the housing further comprises a first housing comprising the coupling region and a second housing, and

wherein the electronic device comprises:

a hinge structure connecting the first housing and the second housing; and

a display comprising a first area disposed in the first housing, a second area disposed in the second housing, and a flexible area between the first area and the second area.